

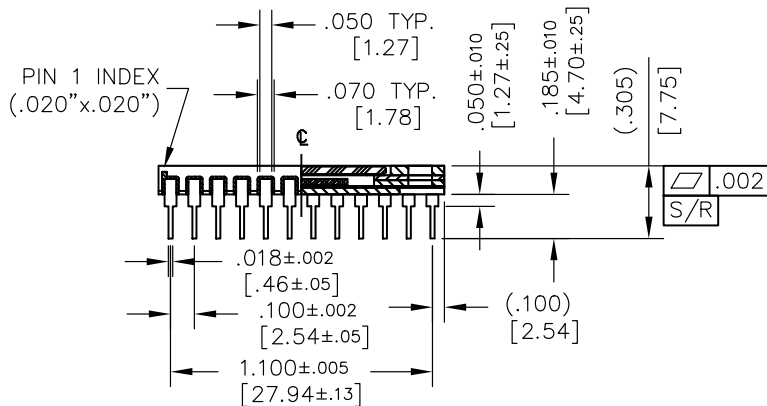
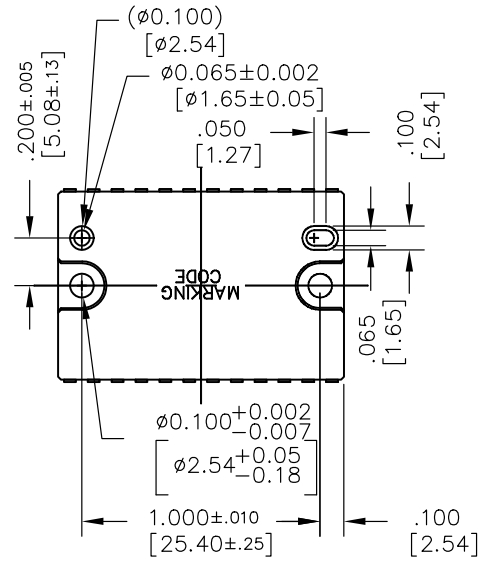
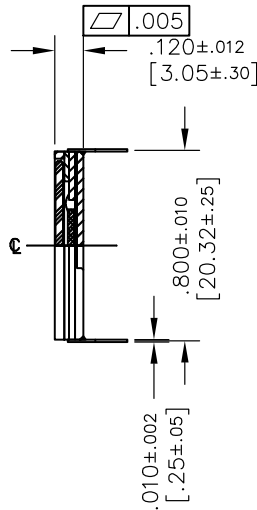
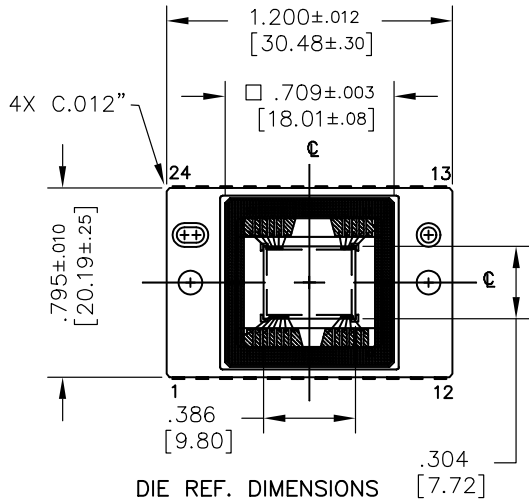
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



CERAMIC DIP 24, 30.48x20.19
CASE 125AW
ISSUE O

DATE 30 JUL 2014



NOTES:

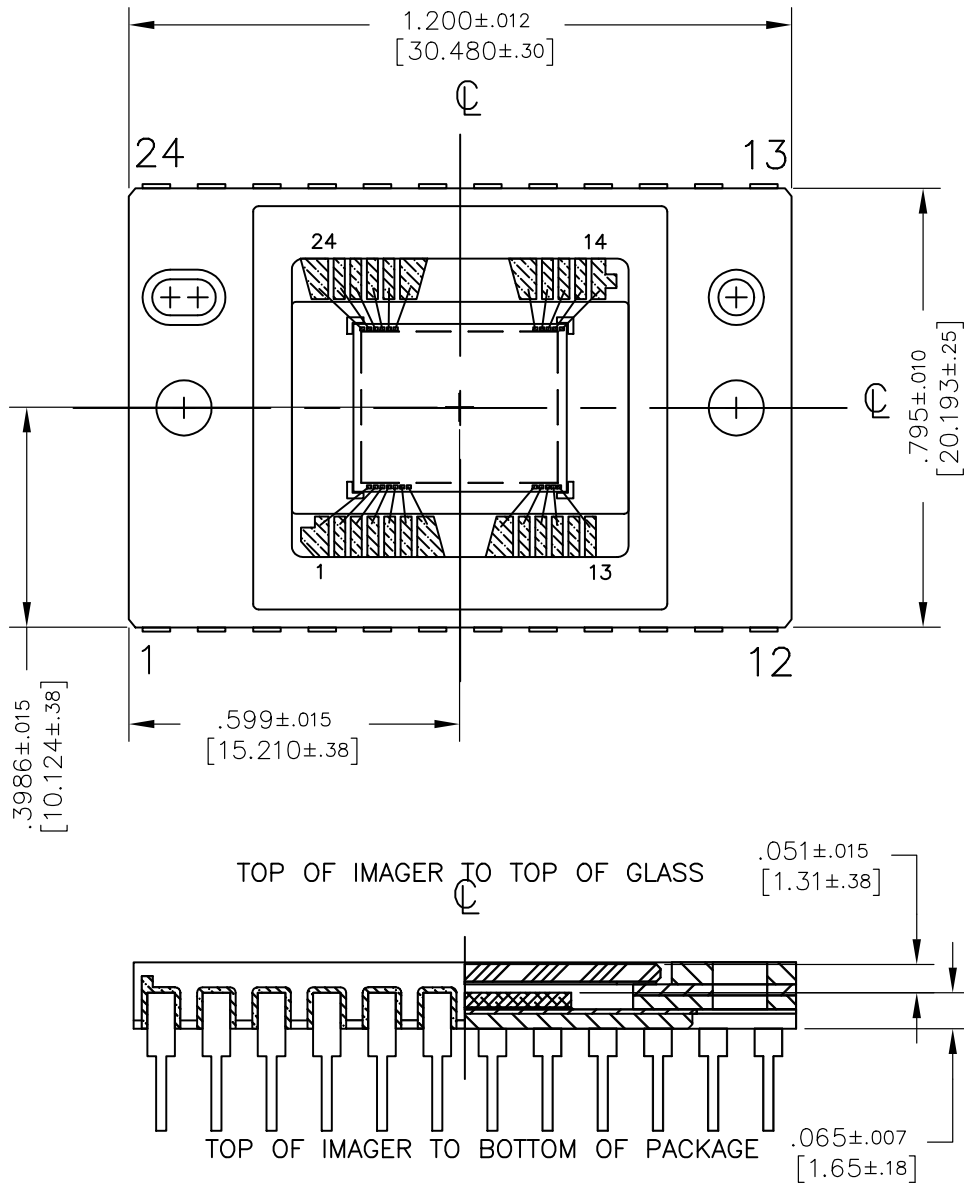
- COVER GLASS IS MANUALLY PLACED AND VISUALLY ALIGNED OVER DIE – LOCATION ACCURACY IS NOT GUARANTEED.

Dimensions in: Inches [mm]

| | | |
|-------------------------|------------------------------------|--|
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CERAMIC DIP 24, 30.48x20.19
CASE 125AW
ISSUE O

DATE 30 JUL 2014



NOTES:

1. CENTER OF IMAGE IS OFFSET FROM CENTER OF PACKAGE BY $(-.030, .028)$ mm NOMINAL.
2. DIE IS ALIGNED WITHIN ± 2 DEGREE OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

| | | |
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